

# Product Specification

XBLW SN74LS32

Quad 2-input Or Gate

WEB | [www.xinboleic.com](http://www.xinboleic.com)



## Description

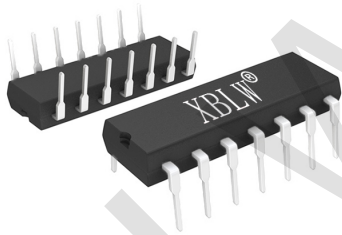
The SN74LS32 is a quad 2-input OR gate. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## Features

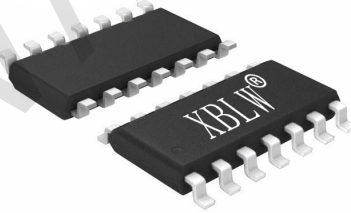
- Buffered inputs
- Wide operating voltage range: 2 V to 6 V
- Specified from -20°C to +85°C
- Packaging information: DIP-14/SOP-14/TSSOP-14

## Applications

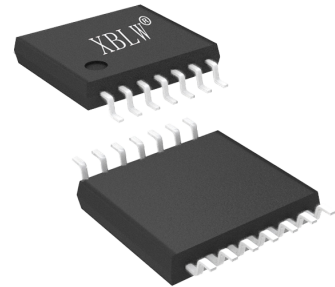
- User fewer inputs to monitor error signals
- Combine active-low enable signals



DIP-14



SOP-14



TSSOP-14

## Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS32N	DIP-14	74LS32N	Tube	1000Pcs/Box
XBLW SN74LS32DTR	SOP-14	74LS32	Tape	2500Pcs/Reel
XBLW SN74LS32TDTR	TSSOP-14	74LS32	Tape	3000Pcs/Reel

### Block Diagram

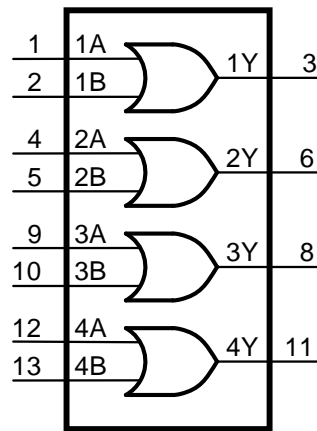


Figure 1. Logic symbol

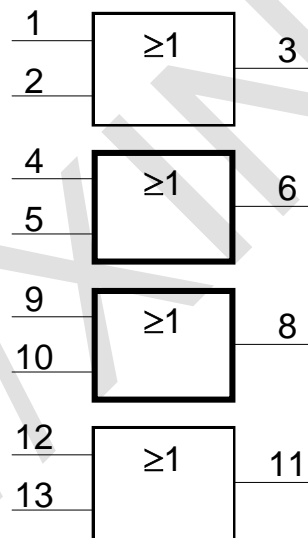


Figure 2. IEC logic symbol

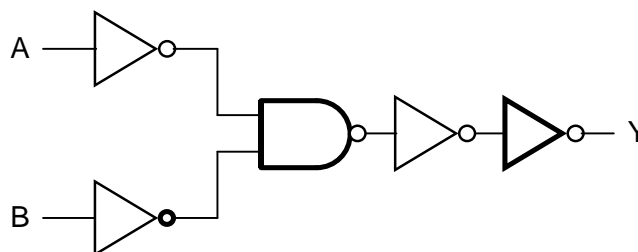
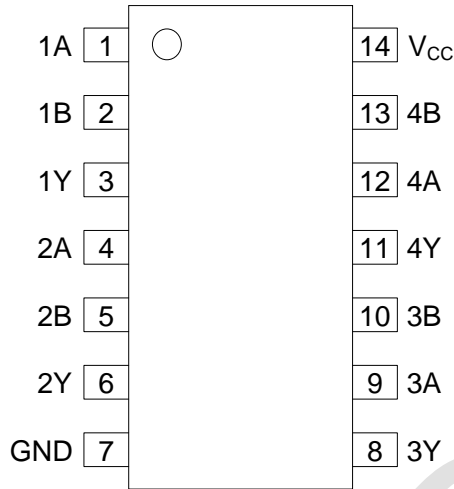


Figure 3. Logic diagram for one gate

## Pin Configurations



## Pin Description

Pin No.	Pin Name	Description
1	1A	data input
2	1B	data input
3	1Y	data output
4	2A	data input
5	2B	data input
6	2Y	data output
7	GND	ground (0V)
8	3Y	data output
9	3A	data input
10	3B	data input
11	4Y	data output
12	4A	data input
13	4B	data input
14	V <sub>CC</sub>	supply voltage

## Function Table

Input		Output
nA	nB	nY
L	L	L
L	H	H
H	L	H
H	H	H

Note: H=HIGH voltage level; L=LOW voltage level.

## Electrical Parameter

### Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	$V_{CC}$	-	-0.5	+7	V
input clamping current	$I_{IK}$	$V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	-	$\pm 20$	mA
output clamping current	$I_{OK}$	$V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	-	$\pm 20$	mA
output current	$I_O$	$-0.5V < V_O < V_{CC} + 0.5V$	-	$\pm 25$	mA
supply current	$I_{CC}$	-	-	50	mA
ground current	$I_{GND}$	-	-50	-	mA
total power dissipation	$P_{tot}$	-	-	500	mW
storage temperature	$T_{stg}$	-	-65	+150	°C
soldering temperature	$T_L$	10s	DIP	245	°C
			SOP/TSSOP	260	

### Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	$V_{CC}$	-	2.0	5.0	6.0	V
input voltage	$V_I$	-	0	-	$V_{CC}$	V
output voltage	$V_O$	-	0	-	$V_{CC}$	V
input transition rise and fall rate	$\Delta t / \Delta V$	$V_{CC} = 2.0V$	-	-	625	ns/V
		$V_{CC} = 4.5V$	-	1.67	139	ns/V
		$V_{CC} = 6.0V$	-	-	83	ns/V
ambient temperature	$T_{amb}$	-	-20	-	+85	°C

## Electrical Characteristics

### DC Characteristics 1

( $T_{amb}=25^{\circ}\text{C}$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	$V_{IH}$	$V_{CC}=2.0\text{V}$	1.5	1.2	-	V	
		$V_{CC}=4.5\text{V}$	3.15	2.4	-	V	
		$V_{CC}=6.0\text{V}$	4.2	3.2	-	V	
LOW-level input voltage	$V_{IL}$	$V_{CC}=2.0\text{V}$	-	0.8	0.5	V	
		$V_{CC}=4.5\text{V}$	-	2.1	1.35	V	
		$V_{CC}=6.0\text{V}$	-	2.8	1.8	V	
HIGH-level output voltage	$V_{OH}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	2.0	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	4.5	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	6.0	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.98	4.32	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.48	5.81	-	V
LOW-level output voltage	$V_{OL}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	0	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	0.15	0.26	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	0.16	0.26	V
input leakage current	$I_I$	$V_I=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	$\pm 1$	$\mu\text{A}$	
supply current	$I_{CC}$	$V_I=V_{CC}$ or GND; $I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	2.0	$\mu\text{A}$	
input capacitance	$C_I$	-	-	3.5	-	pF	

### DC Characteristics 2

( $T_{amb}=-20^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	$V_{IH}$	$V_{CC}=2.0\text{V}$	1.5	-	-	V	
		$V_{CC}=4.5\text{V}$	3.15	-	-	V	
		$V_{CC}=6.0\text{V}$	4.2	-	-	V	
LOW-level input voltage	$V_{IL}$	$V_{CC}=2.0\text{V}$	-	-	0.5	V	
		$V_{CC}=4.5\text{V}$	-	-	1.35	V	
		$V_{CC}=6.0\text{V}$	-	-	1.8	V	
HIGH-level output voltage	$V_{OH}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	-	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	-	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	-	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.84	-	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.34	-	-	V
LOW-level output voltage	$V_{OL}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	-	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	-	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	-	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	-	0.33	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	-	0.33	V
input leakage current	$I_I$	$V_I=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	$\pm 1$	$\mu\text{A}$	
supply current	$I_{CC}$	$V_I=V_{CC}$ or GND; $I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	20	$\mu\text{A}$	

### AC Characteristics 1

( $T_{amb}=25^{\circ}C$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
nA, nB to nY propagation delay	$t_{pd}$	see Figure 5 <sup>[1]</sup>	$V_{CC}=2.0V$	-	22	90	ns
			$V_{CC}=4.5V$	-	8	18	ns
			$V_{CC}=5.0V; C_L=15pF$	-	6	-	ns
			$V_{CC}=6.0V$	-	6	15	ns
transition time	$t_t$	see Figure 5 <sup>[2]</sup>	$V_{CC}=2.0V$	-	19	75	ns
			$V_{CC}=4.5V$	-	7	15	ns
			$V_{CC}=6.0V$	-	6	13	ns
power dissipation capacitance	$C_{PD}$	per package; $V_I = GND$ to $V_{CC}$ <sup>[3]</sup>	-	16	-	pF	

Note:

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

[2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .

[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in uW).

$P_D=(C_{PD} \times V_{CC}^2 \times f_i \times N) + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  $f_i$ =input frequency in MHz;

$f_o$ =output frequency in MHz;

$C_L$ =output load capacitance in pF;  $V_{CC}$ =supply voltage in V;

$N$ =number of inputs switching;  $\Sigma(C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.

### AC Characteristics 2

( $T_{amb}=-20^{\circ}C$  to  $+85^{\circ}C$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
nA, nB to nY propagation delay	$t_{pd}$	see Figure 5 <sup>[1]</sup>	$V_{CC}=2.0V$	-	-	115	ns
			$V_{CC}=4.5V$	-	-	23	ns
			$V_{CC}=6.0V$	-	-	20	ns
transition time	$t_t$	see Figure 5 <sup>[2]</sup>	$V_{CC}=2.0V$	-	-	95	ns
			$V_{CC}=4.5V$	-	-	19	ns
			$V_{CC}=6.0V$	-	-	16	ns

Note:

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

[2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .

### Measurement Points

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
SN74LS32	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$

### Test Data

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
SN74LS32	$V_{CC}$	6.0ns	15pF, 50pF	$t_{PLH}, t_{PHL}$

## Testing Circuit

### AC Testing Circuit

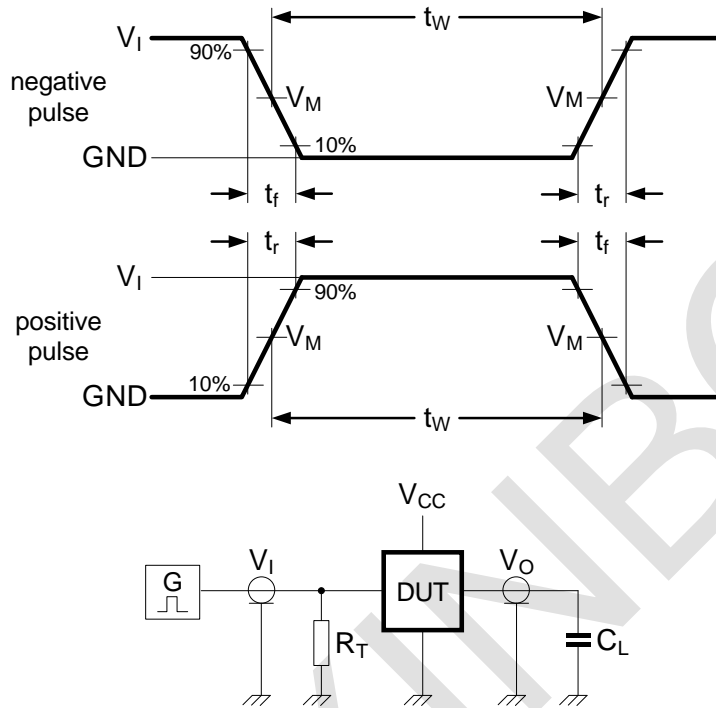


Figure 4. Test circuit for measuring switching times

Definitions for test circuit:

$C_L$ =load capacitance including jig and probe capacitance.

$R_T$ =termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

### AC Testing Waveforms

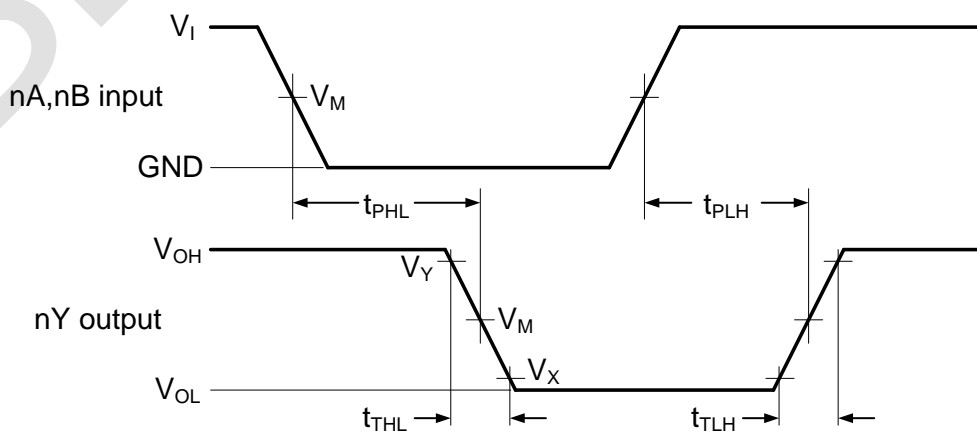


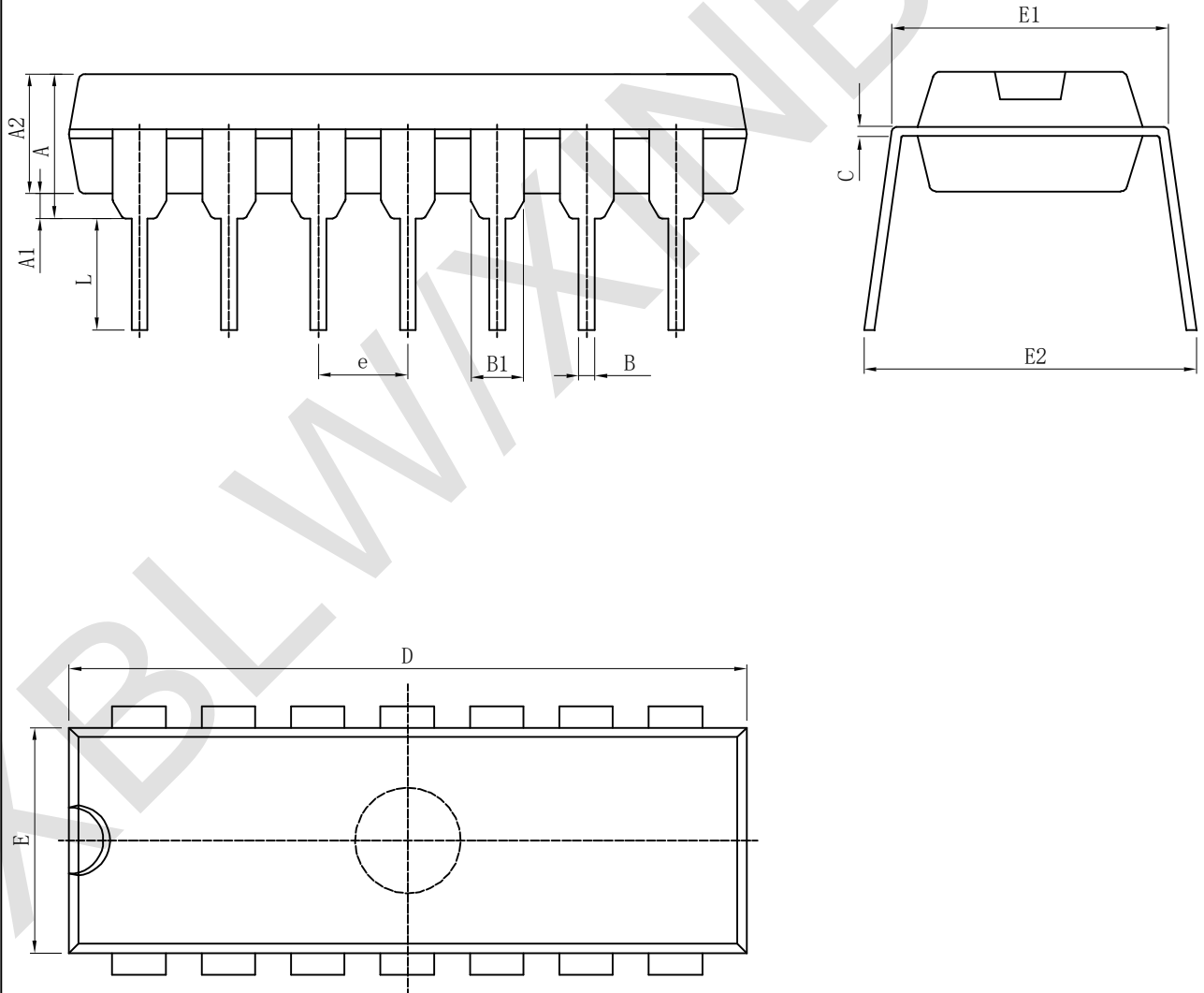
Figure 5. Input to output propagation delays



**Package Information**

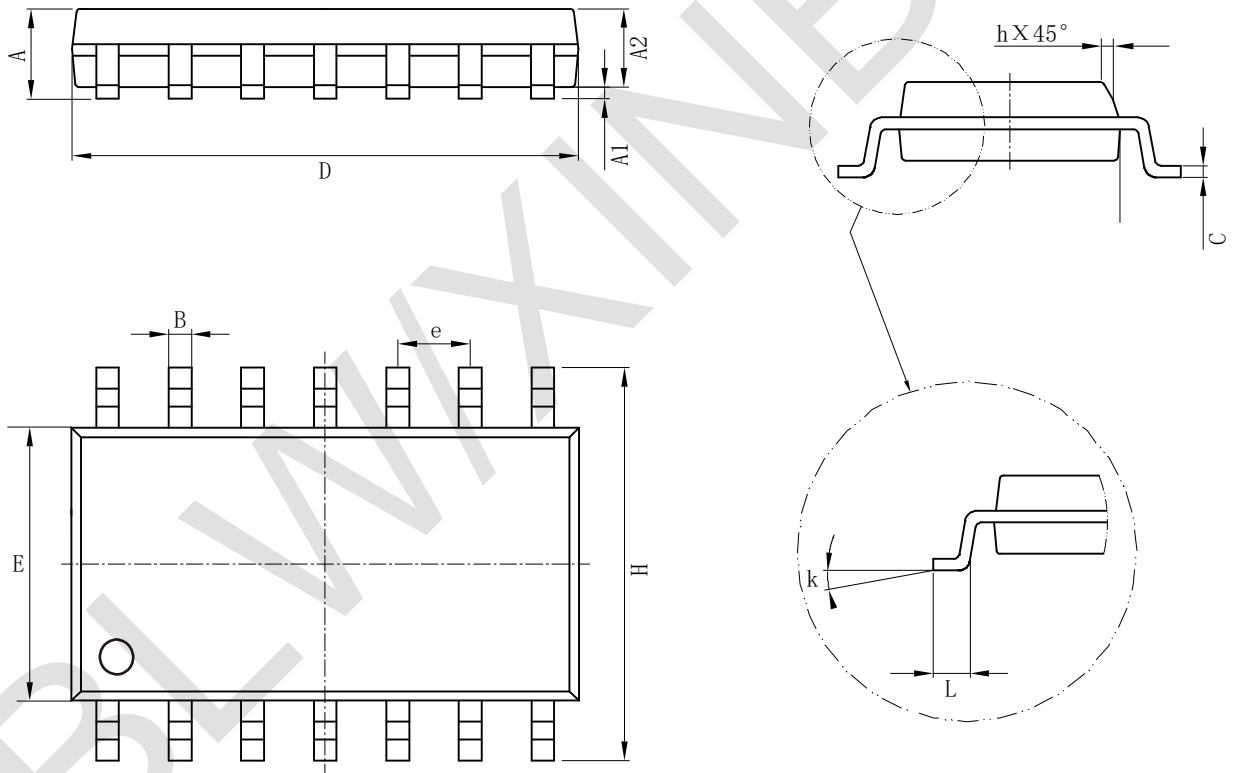
· DIP-14

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A	3.710	4.310	A	0.146	0.170
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.380	0.570	B	0.015	0.022
B1	1.524 (BSC)		B1	0.060 (BSC)	
C	0.204	0.360	C	0.008	0.014
D	18.800	19.200	D	0.740	0.756
E	6.200	6.600	E	0.244	0.260
E1	7.320	7.920	E1	0.288	0.312
e	2.540 (BSC)		e	0.100 (BSC)	
L	3.000	3.600	L	0.118	0.142
E2	8.400	9.000	E2	0.331	0.354



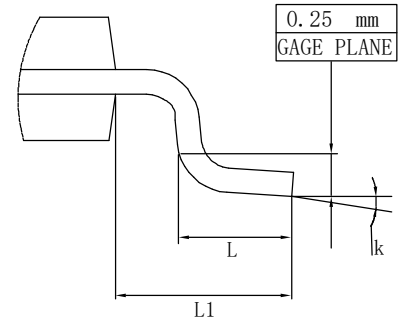
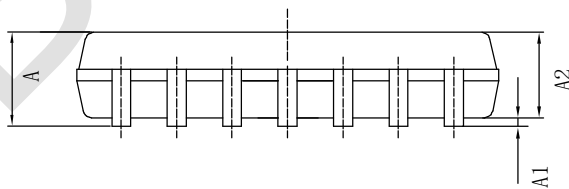
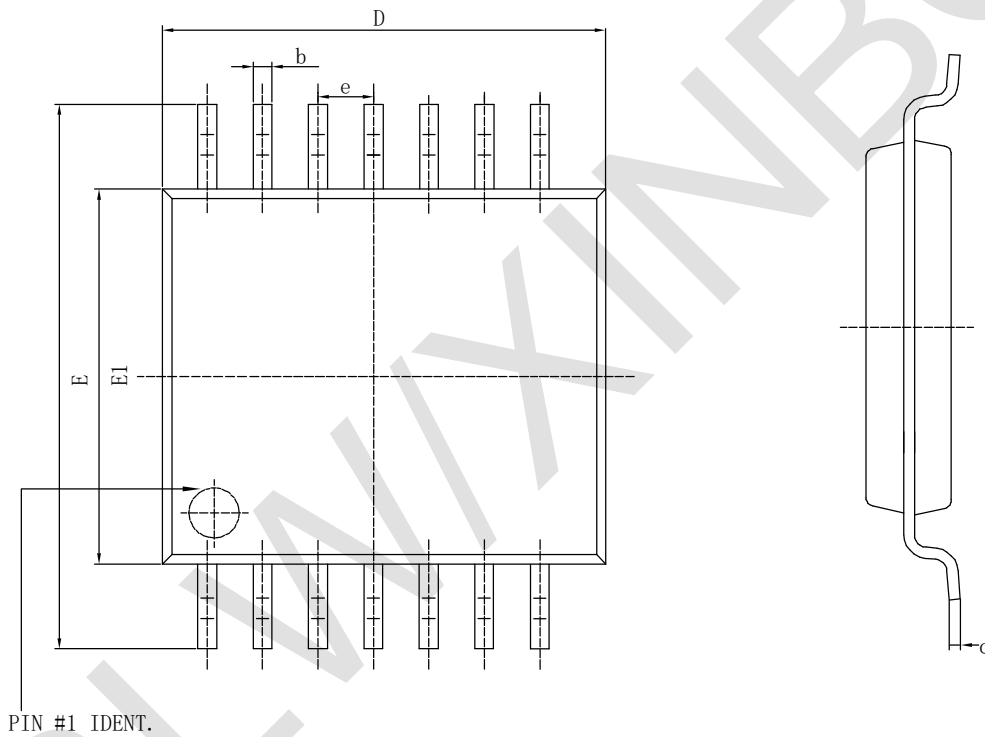
· SOP-14

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A	1.350	1.750	A	0.050	0.068
A1	0.100	0.250	A1	0.004	0.009
A2	1.100	1.650	A2	0.040	0.060
B	0.330	0.510	B	0.010	0.020
C	0.190	0.250	C	0.007	0.009
D	8.550	8.750	D	0.330	0.340
E	3.800	4.000	E	0.150	0.150
e	1.27		e	0.05	
H	5.800	6.200	H	0.220	0.240
h	0.250	0.500	h	0.009	0.020
L	0.400	1.270	L	0.015	0.050
k	8° (max)		k	8° (max)	



· TSSOP-14

Symbol	Size	Dimensions In Millimeters		Symbol	Size	Dimensions In Inches	
		Min (mm)	Max (mm)			Min (in)	Max (in)
A			1.200	A			0.047
A1		0.050	0.150	A1		0.002	0.006
A2		0.800	1.050	A2		0.031	0.041
b		0.190	0.300	b		0.007	0.012
c		0.090	0.200	c		0.004	0.0089
D		4.900	5.100	D		0.193	0.201
E		6.200	6.600	E		0.244	0.260
E1		4.300	4.500	E1		0.169	0.176
e		0.65		e		0.0256	
L		0.450	0.750	L		0.018	0.030
L1		1.00		L1		0.039	
k		0°	8°	k		0°	8°



## Statement

- XBLW reserves the right to modify the product manual without prior notice! Before placing an order, customers need to confirm whether the obtained information is the latest version and verify the completeness of the relevant information.
- Any semi-guide product is subject to failure or malfunction under specified conditions. It is the buyer's responsibility to comply with safety standards when using XBLW products for system design and whole machine manufacturing. And take the appropriate safety measures to avoid the potential in the risk of loss of personal injury or loss of property situation!
- XBLW product has not been licensed for life support, military and aerospace applications, and therefore XBLW is not responsible for any consequences arising from its use in these areas.
- If any or all XBLW products (including technical data, services) described or contained in this document are subject to any applicable local export control laws and regulations, they may not be exported without an export license from the relevant authorities in accordance with such laws.
- The specifications of any and all XBLW products described or contained in this document specify the performance, characteristics, and functionality of said products in their standalone state, but do not guarantee the performance, characteristics, and functionality of said products installed in Customer's products or equipment. In order to verify symptoms and conditions that cannot be evaluated in a standalone device, the Customer should ultimately evaluate and test the device installed in the Customer's product device.
- XBLW documentation is only allowed to be copied without any alteration of the content and with the relevant authorization. XBLW assumes no responsibility or liability for altered documents.
- XBLW is committed to becoming the preferred semiconductor brand for customers, and XBLW will strive to provide customers with better performance and better quality products.